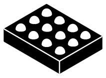
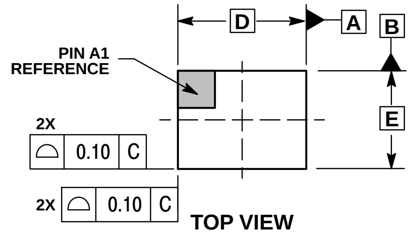


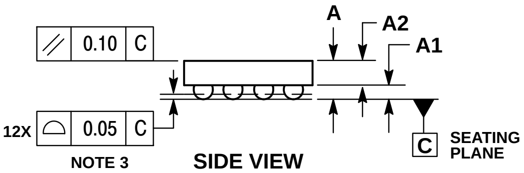
SCALE 4:1

12 PIN FLIP−CHIP, 2.02x1.54, 0.5P
CASE 499AU
ISSUE O

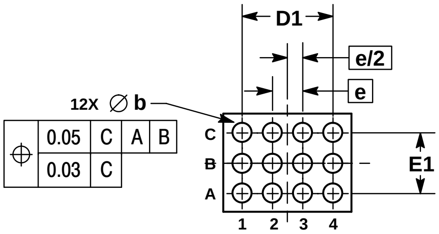
DATE 19 MAR 2007



TOP VIEW



SIDE VIEW



BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS	
DIM	MIN	MAX
A	−−−	0.66
A1	0.21	0.27
A2	0.33	0.39
b	0.29	0.34
D	2.02 BSC	
D1	1.50 BSC	
E	1.54 BSC	
E1	1.00 BSC	
e	0.50 BSC	

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DESCRIPTION:	**12 PIN FLIP−CHIP, 2.02 X 1.54, 0.5P**	**PAGE 1 OF 1**

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